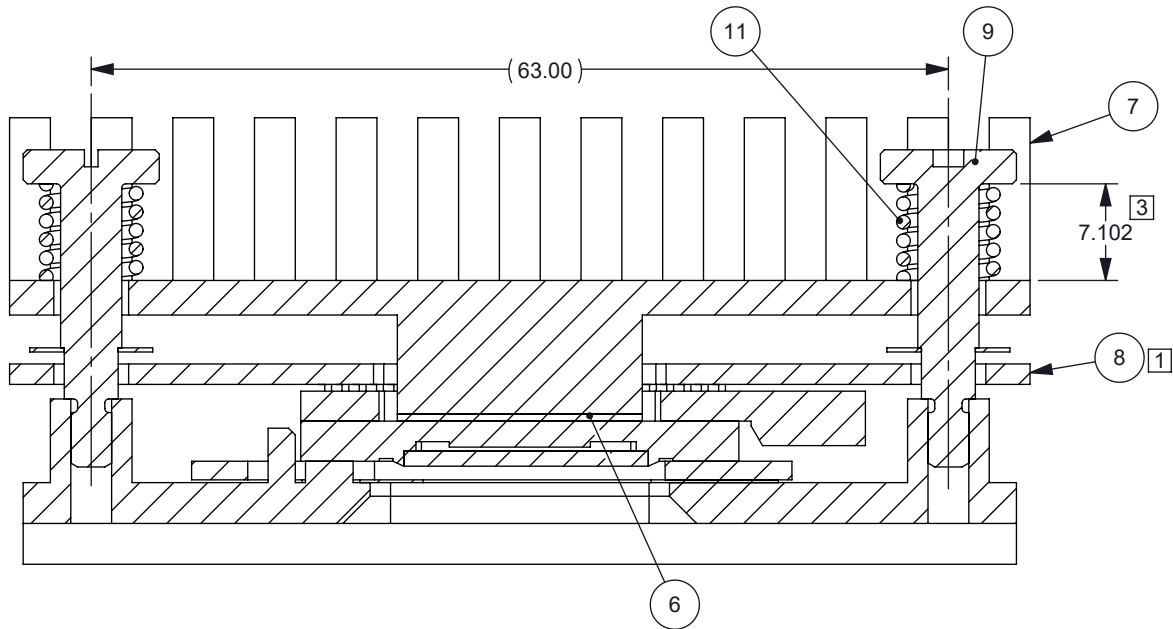
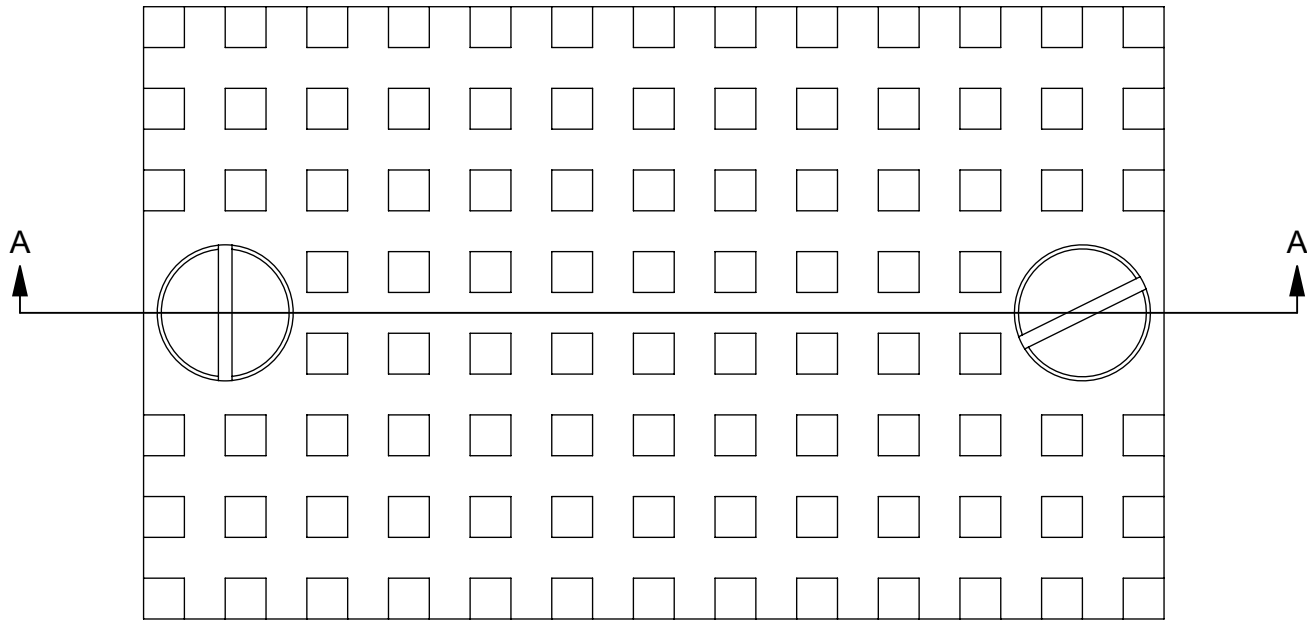
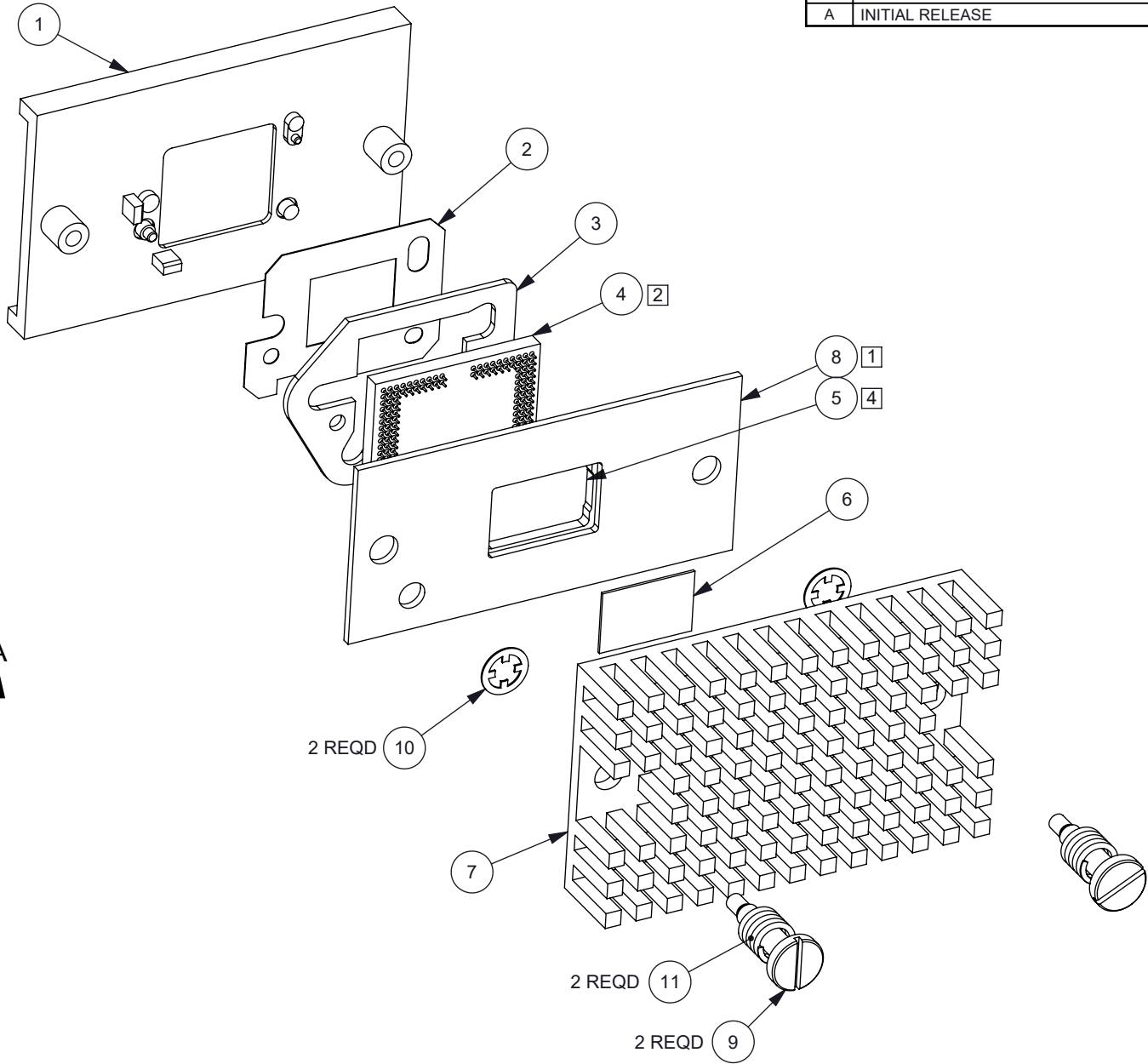


NOTES: UNLESS OTHERWISE SPECIFIED:

- [1] SOME TYPE OF SUPPORT FOR THE DMD PC BOARD IS NEEDED TO ASSURE THE PC BOARD IS SECURED IN POSITION TO MAINTAIN THE DMD ELECTRICAL CONNECTION AFTER MECHANICAL SHOCK AND VIBRATION. SEE TI DRAWING 2507519 FOR CONCEPT IDEAS. THESE CONCEPTS WILL NEED TO BE ADAPTED FOR THIS DMD. CARE SHOULD BE TAKEN TO ENSURE THE METHOD DOES NOT APPLY LOADS TO THE DMD THAT EXCEED DMD SPECIFICATION
- [2] CARE SHOULD BE TAKEN WHEN INSTALLING THE DMD TO NOT DAMAGE THE DMD WINDOW DUE TO THE CLOSE PROXIMITY OF THE ALIGNMENT AND GUIDE FEATURES ON THE INTERFACE
- [3] CRITICAL GAP FOR COIL SPRING DESIGN TO CONTROL LOADS ON THE DMD THERMAL INTERFACE AREA. THE SIZE OF THE GAP WILL VARY DEPENDING ON SIZE VARIATION OF PARTS TOLERANCES AND SPRING
- [4] ZERO INSERTION FORCE (ZIF) STYLE SHOWN; LOW INSERTION FORCE (LIF) STYLE (DWG # 2509473) WILL ALSO WORK



SECTION A-A



2	11	LC-040D-2-S	COIL SPRING (LEE SPRING)	
2	10	5105-15	RETAINER RING (TRUARC)	
2	9	2508220	SHOULDER SCREW, PUSH NUT	
1	8	2509478	PC BOARD, SYSTEM OUTLINE	
1	7	2509476	HEAT SINK	
1	6	2509477	THERMAL PAD	
1	5	2509474	SOCKET ASSEMBLY ICD	4
1	4	-	DMD, SERIES 451	
1	3	2509649	GASKET, EDGE GUIDE	
1	2	2509647	APERTURE, EDGE GUIDE	
1	1	2509651	INTERFACE, EDGE GUIDE	
QTY	ITEM	PART NUMBER	DESCRIPTION	Notes

UNLESS OTHERWISE SPECIFIED		Part List		TEXAS INSTRUMENTS	
		DWN J. McKinley	DATE 2/5/2019		
		Engr			
		CQE/QA			
NEXT ASSY USED ON APPLICATION		CM		ASSEMBLY, SERIES 451 DMD MOUNTING CONCEPT, EDGE GUIDE	
		Apprvd McKinley	2/7/2019		
		SIZE B	DWG NO 2516585	REV A	
		SCALE 1:2		SHEET 1 OF 2	

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DWG NO

SH2

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SSZZ031 January 01, 2013

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DWNJ. McKINLEY

DATE2/5/2019

SIZEB

DRAWING NO

REV A

SCALENone

SHEET2 OF 2

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